

10 9 8 7 6 5 4 3 2 1

**NOTES :**

1. MATERIAL :  
 HOUSING : (a) HIGH TEMP. NYLON ,GLASS FIBER FILLED,UL94V-0, COLOR: BLACK,  
 (b) POLYESTER , GLASS FIBER FILLED,UL94V-0, COLOR: WHITE,  
 TERMINAL : PHOSPHOR BRONZE  
 METAL SHELL : COPPER ALLOY

2. PLATING :

TERMINAL :  
 CONTACT AREA : (a) GOLD FLASH.  
 (b) GLOD (Au), THICKNESS = 30 MICROINCH MINIMUM.  
 /0.76 MICROMETER MINIMUM.

SOLDER TAIL :  
 PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM .  
 /1.9 MICROMETER MINIMUM.

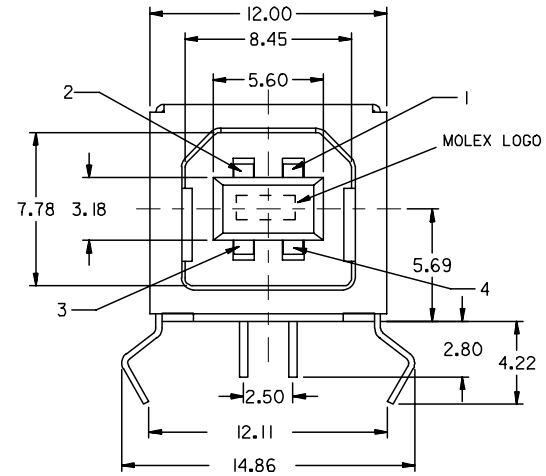
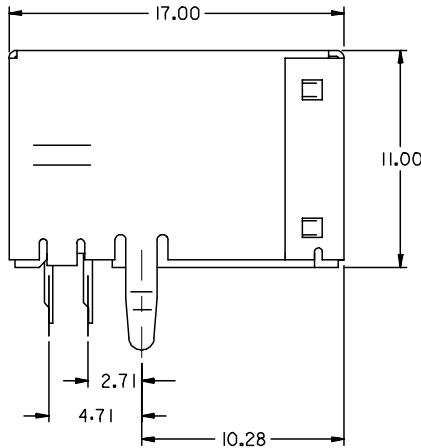
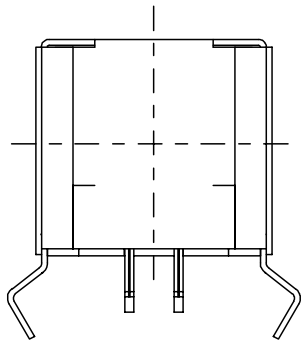
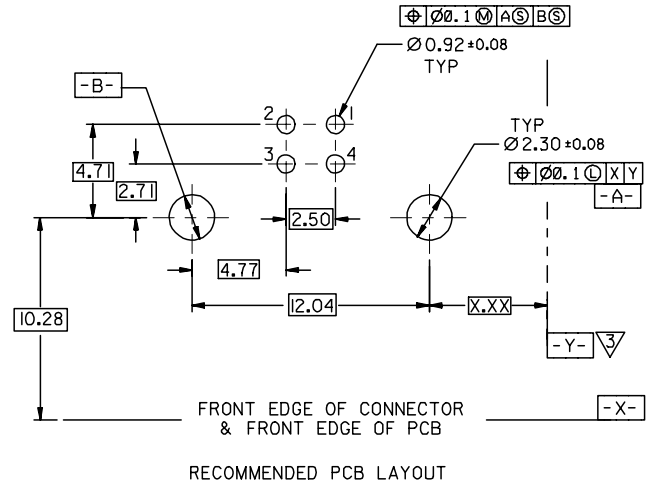
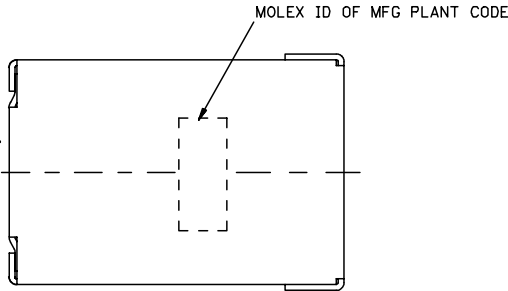
UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.  
 /1.27 MICROMETER MINIMUM.

METAL SHELL :  
 PURE TIN(Sn) , THICKNESS= 50 MICROINCH MINIMUM.  
 /1.27 MICROMETER MINIMUM.

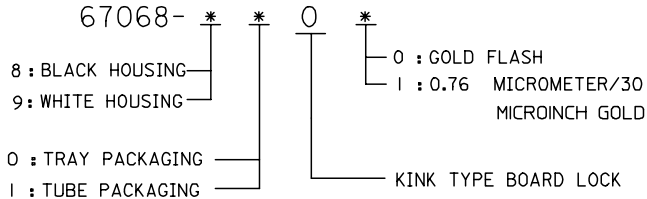
UNDER PLATE : NICKEL (Ni) , THICKNESS= 50 MICROINCH MINIMUM.  
 /1.27 MICROMETER MINIMUM.

▽ DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER  
 RECOMMENDED PCB THICKNESS : 1.60±0.05

4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000



**PART NUMBER LEGEND:**



NEW RELEASE	DESCRIPTION
EC NO: SH2005-0142	DRWN: DAVID HU 2004/11/5
CHKD: HARVEY 2004/11/25	APPR: TYAP 2004/11/25
A	REV

QUALITY SYMBOLS
▽=0
▽C=0

GENERAL TOLERANCES (UNLESS SPECIFIED)
4 PLACES ± --- ± ---
3 PLACES ± --- ± ---
2 PLACES ± 0.25 ± ---
1 PLACE ± 0.25 ± ---
ANGULAR ± 3 °
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
MM ONLY	4:1	METRIC	
DRAWN BY	DATE	TITLE	
DAVID HU	2004/11/05	USB B TYPE CONNECTOR	
CHECKED BY	DATE	KINK TYPE BOARD LOCK	
HARVEY	2004/11/05	(LEAD-FREE)	
APPROVED BY	DATE		
MATERIAL NO.	DOCUMENT NO.	MOLEX INCORPORATED	
	SD-67068-003	SHEET NO. 1 OF 4	

SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
A3			

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

NOTES :

1. MATERIAL :  
 HOUSING : (a) HIGH TEMP. NYLON, GLASS FIBER FILLED, UL94V-0, COLOR: BLACK,  
 (b) POLYESTER, GLASS FIBER FILLED, UL94V-0, COLOR: WHITE,  
 TERMINAL : PHOSPHOR BRONZE  
 METAL SHELL : COPPER ALLOY

2. PLATING :  
 TERMINAL :  
 CONTACT AREA : (a) GOLD FLASH.  
 (b) GLOD (Au), THICKNESS = 30 MICROINCH MINIMUM.  
 /0.76 MICROMETER MINIMUM.

SOLDER TAIL :  
 PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM .  
 /1.9 MICROMETER MINIMUM.

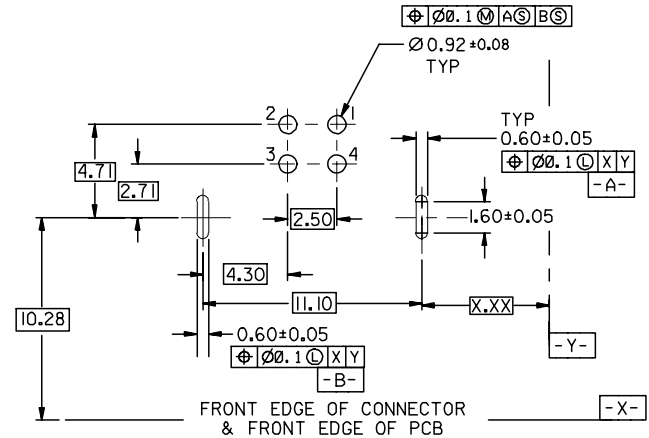
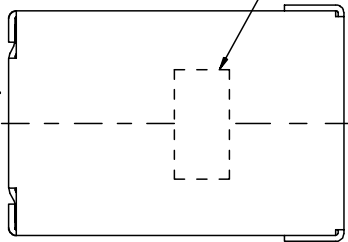
UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.  
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METAL SHELL :  
 PURE TIN(Sn) THICKNESS= 50 MICROINCH MINIMUM.  
 /1.27 MICROMETER MINIMUM.

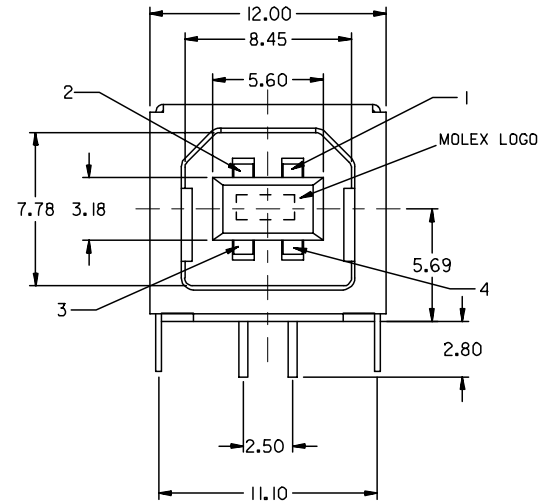
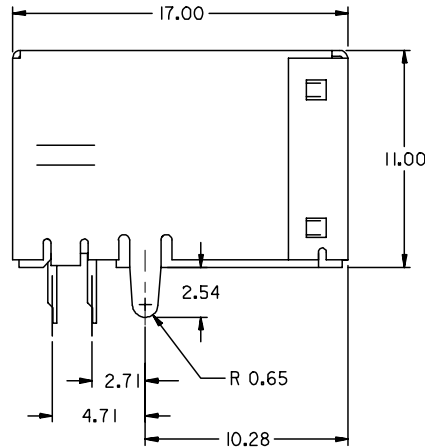
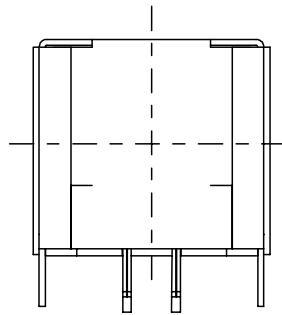
UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.  
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3 DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER  
 RECOMMENDED PCB THICKNESS : 1.60±0.05  
 4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000

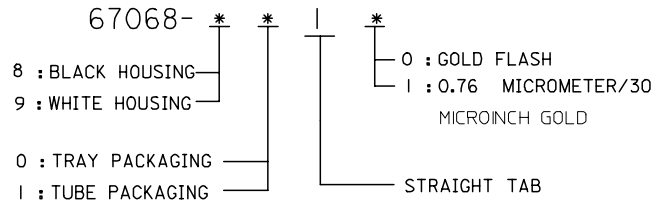
MOLEX ID OF MFG PLANT CODE



RECOMMENDED PCB LAYOUT



PART NUMBER LEGEND:



NEW RELEASE	DESCRIPTION
EC NO: SH2005-0142	DRWN: DAVID HU 2004/11/05
CHKD: HARVEY 2004/11/05	APPR: TYTAP 2004/11/05
REV	DESCRIPTION
A	

QUALITY SYMBOLS
▽=0
▽C=0

GENERAL TOLERANCES (UNLESS SPECIFIED)
4 PLACES ± --- ± ---
3 PLACES ± --- ± ---
2 PLACES ± 0.25 ± --- 2004/11/05
1 PLACE ± 0.25 ± ---
ANGULAR ± 3 °
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE MM ONLY	SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
DRAWN BY DAVID HU 2004/11/05	DATE 2004/11/05	TITLE USB B TYPE CONNECTOR WITH STRAIGHT TAB (LEAD-FREE)	
CHECKED BY	DATE 2004/11/05		
APPROVED BY	DATE		
MATERIAL NO.	DOCUMENT NO. SD-67068-003	SHEET NO. 2	

MOLEX INCORPORATED
SEE NOTES
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

9 8 7 6 5 4 3 2 1

8 7 6 5 4 3 2 1

NOTES :  
 1. MATERIAL :  
 HOUSING : (a) HIGH TEMP. NYLON, GLASS FIBER FILLED, UL94V-0, COLOR: BLACK,

TERMINAL : PHOSPHOR BRONZE  
 METAL SHELL : COPPER ALLOY

2. PLATING :  
 TERMINAL :  
 CONTACT AREA : (a) GOLD FLASH.  
 (b) GL0D (Au), THICKNESS = 30 MICROINCH MINIMUM.  
 /0.76 MICROMETER MINIMUM.

SOLDER TAIL :  
 PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM .  
 /1.9 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.  
 /1.27 MICROMETER MINIMUM.

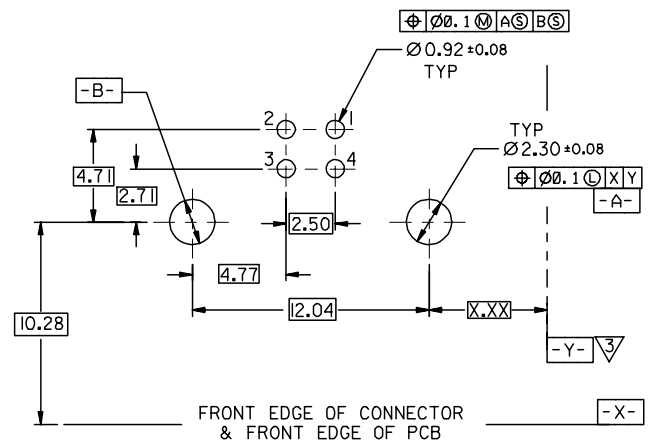
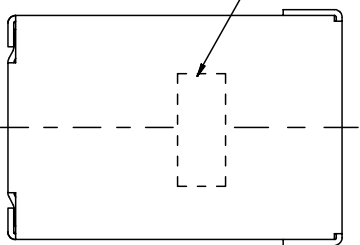
METAL SHELL :  
 PURE TIN(SN), THICKNESS= 50 MICROINCH MINIMUM.  
 /1.27 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.  
 /1.27 MICROMETER MINIMUM.

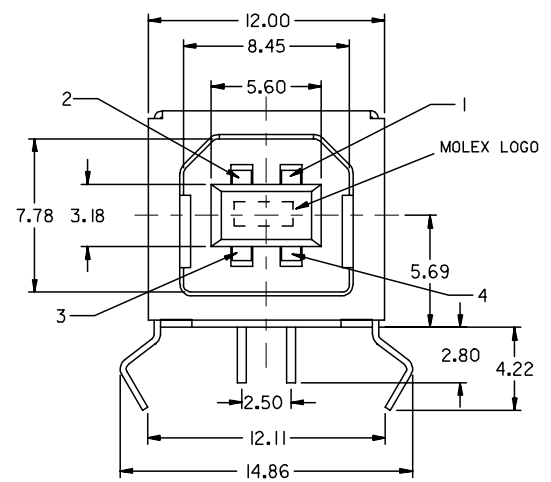
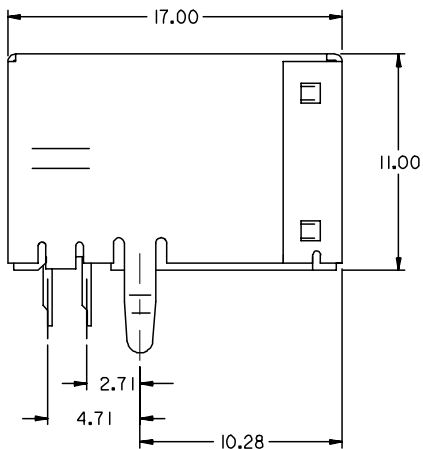
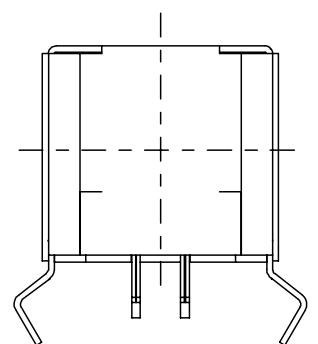
▽ DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER  
 RECOMMENDED PCB THICKNESS : 1.60±0.05

4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000

MOLEX ID OF MFG PLANT CODE



FRONT EDGE OF CONNECTOR  
 & FRONT EDGE OF PCB  
 RECOMMENDED PCB LAYOUT



PART NUMBER LEGEND:  
 67068- 7041

				MATERIAL : SEE NOTES		 MOLEX TAIWAN LTD. SHEET 3 OF 4
				FINISH : SEE NOTES		
				WIRE RANGE :		GENERAL TOLERANCES ANGLE : ± 3° DIM : ± .25/.010
				INS. RANGE :		ENG. NO.: SD-67068-003
A	NEW RELEASE FOR LEAD-FREE		DAVID HU	2004/11/5		REV A
LTR	REVISION RECORD	ECN	DR	DATE	DRAWN BY 2004/11/5 DAVID HU	CHK'D BY
REVISE ONLY ON CAD SYSTEM					APPR'D BY	SCALE 4 : 1
TITLE : HIGH TEMP.USB B TYPE CONNECTOR KINK TYPE BOARD LOCK (LEAD-FREE)						

ENG. NO.  
 EDP NO.  
 SIMILAR ITEM  
 CAD FILE :  
 DO NOT SCALE DRAWING

F  
 E  
 D  
 C  
 B  
 A

ENG. NO SDA-67068-\*\*\*\*

EDP NO.

SIMILAR ITEM

CAD FILE : S6706802

DO NOT SCALE DRAWING

NOTES :

1. MATERIAL :  
HOUSING : (a) HIGH TEMP. NYLON, GLASS FIBER FILLED, UL94V-0, COLOR: BLACK,

TERMINAL : PHOSPHOR BRONZE  
METAL SHELL : COPPER ALLOY

2. PLATING :

TERMINAL :  
CONTACT AREA : (a) GOLD FLASH.  
(b) GL0D (Au), THICKNESS = 30 MICROINCH MINIMUM.  
/0.76 MICROMETER MINIMUM.

SOLDER TAIL :  
PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM .  
/1.9 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.  
/1.27 MICROMETER MINIMUM.

METAL SHELL :  
PURE TIN(Sn) THICKNESS= 50 MICROINCH MINIMUM.  
/1.27 MICROMETER MINIMUM.

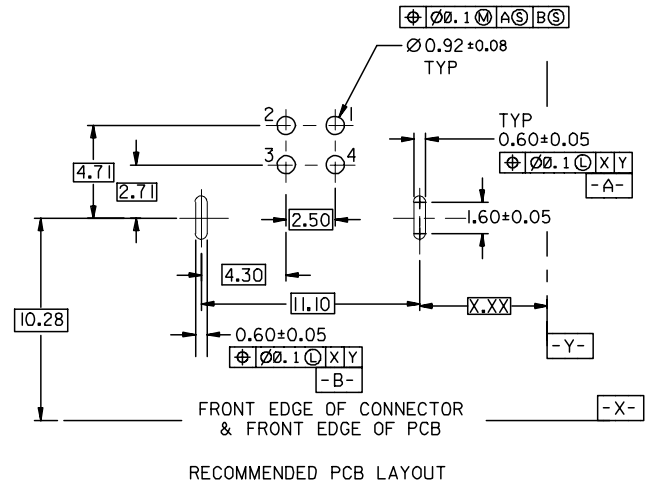
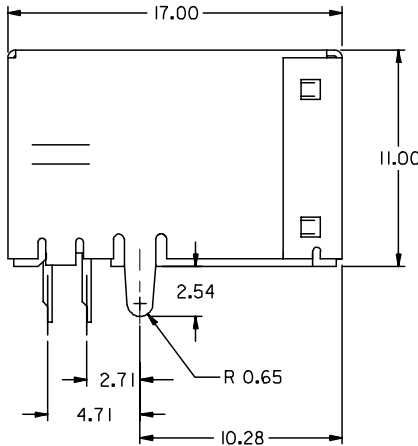
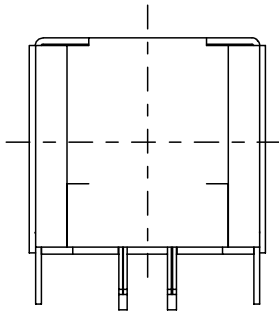
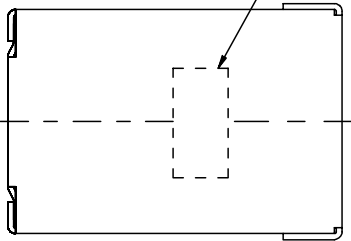
UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.  
/1.27 MICROMETER MINIMUM.

3 DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER

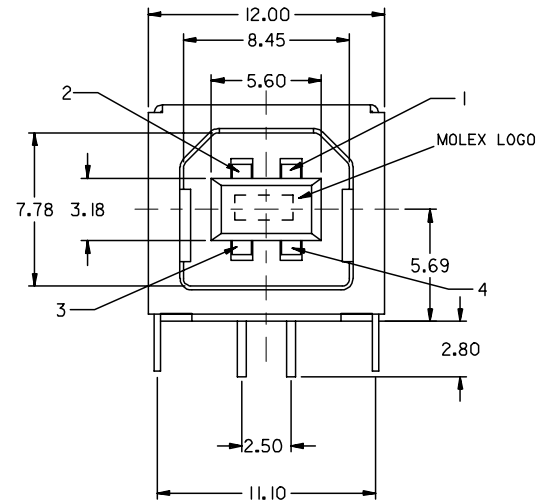
RECOMMENDED PCB THICKNESS : 1.60±0.05

4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000

MOLEX ID OF MFG PLANT CODE



FRONT EDGE OF CONNECTOR & FRONT EDGE OF PCB  
RECOMMENDED PCB LAYOUT



PART NUMBER LEGEND:

67068- 7051

				MATERIAL : SEE NOTES		 MOLEX TAIWAN LTD. SHEET 4 OF 4
				FINISH : SEE NOTES		
				WIRE RANGE :		GENERAL TOLERANCES ANGLE : ± 3° DIM : ± .25/.010
				INS. RANGE :		ENG. NO.: SD-67068-003
A	NEW RELEASE FOR LEAD-FREE		DAVID HU	2004/11/5		REV A
LTR	REVISION RECORD	ECN	DR	DATE	DRAWN BY 2004/11/5 DAVID HU	CHK'D BY
REVISE ONLY ON CAD SYSTEM					APPR'D BY	SCALE 4 : 1
TITLE : HIGH TEMP.USB B TYPE CONNECTOR WITH STRAIGHT TAB (LEAD-FREE)						

NOTES:

1.MATERIAL:

HOUSING:

- (a)HIGH TEMP,NYLON,GLASS FIBRE FILLED,UL94V-0,COLOR: 8#BLACK
  - (b)POLYESTER(PBT),30% GLASS FIBER FILLED,UL94V-0,COLOR: 9#WHITE
- TERMINAL: PHOSPHOR BRONZE  
METAL SHELL: COPPER ALLOY

2.PLATING:

TERMINAL:

- (c)GOLD FLASH ON CONTACT AREA,75 MICROINCH MINIMUM PURE TIN(Sn) ON SOLDER TAIL,UNDER 50 MICROINCH MINIMUM NICKEL(Ni) PLATE.
- (d)30 MICROINCH MINIMUM GOLD(Au) ON CONTACT AREA,75 MICROINCH MINIMUM PURE TIN(Sn) ON SOLDER TAIL,UNDER 50 MICROINCH MINIMUM NICKEL(Ni) PLATE.
- (e)GOLD FLASH ON CONTACT AREA,75 MICROINCH MINIMUM MATTE TIN(Sn) ON SOLDER TAIL,UNDER 50 MICROINCH MINIMUM NICKEL(Ni) PLATE.
- (f)30 MICROINCH MINIMUM GOLD(Au) ON CONTACT AREA,75 MICROINCH MINIMUM MATTE TIN(Sn) ON SOLDER TAIL,UNDER 50 MICROINCH MINIMUM NICKEL(Ni) PLATE.

METAL SHELL:

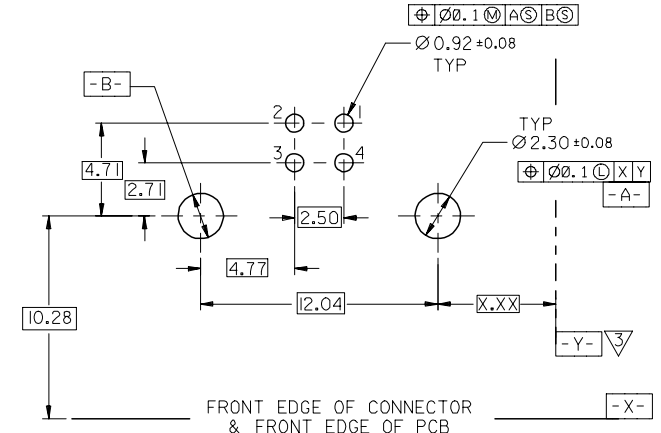
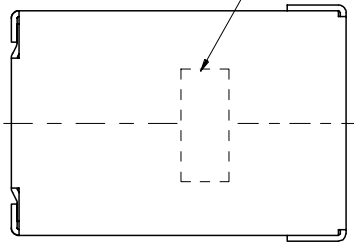
- (g)50 MICROINCH MINIMUM PURE TIN(Sn),UNDER 50 MICROINCH MINIMUM NICKEL(Ni) PLATE.
- (h)50 MICROINCH MINIMUM MATTE TIN(Sn),UNDER 50 MICROINCH MINIMUM NICKEL(Ni) PLATE.

3. DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER.

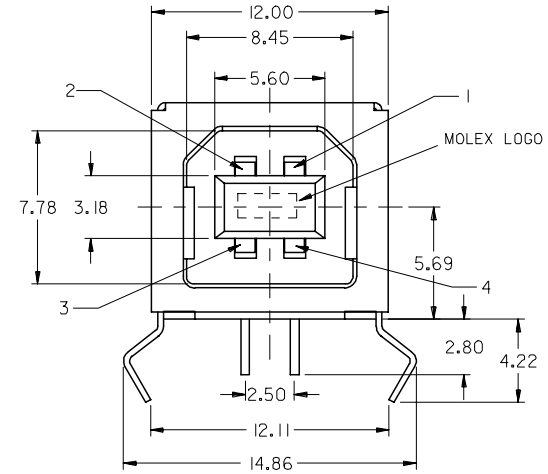
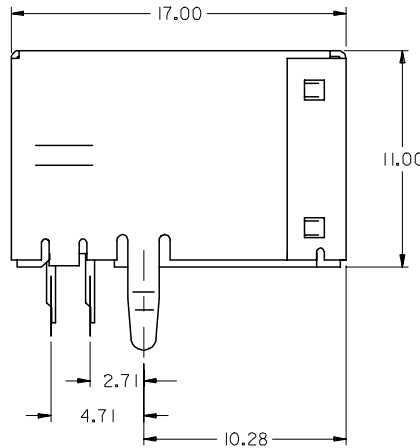
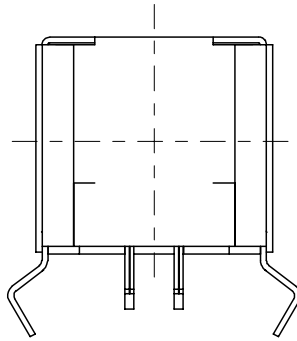
RECOMMENDED PCB THICKNESS : 1.60±0.05

4.PRODUCT SPECIFICATION : REFER TO PS-67998-0000

MOLEX ID OF MFG PLANT CODE



FRONT EDGE OF CONNECTOR & FRONT EDGE OF PCB  
RECOMMENDED PCB LAYOUT



P/N	HOUSING COLOR	PLATING
67068-8000	BLACK	GOLD FLASH SEE NOTES(2-(c),2-(g))
67068-8001	BLACK	30MICROINCH Au SEE NOTES(2-(d),2-(g))
67068-9000	WHITE	GOLD FLASH SEE NOTES(2-(c),2-(g))
67068-9001	WHITE	30MICROINCH Au SEE NOTES(2-(d),2-(g))
67068-8012	BLACK	30MICROINCH Au SEE NOTES(2-(f),2-(h))
67068-8013	BLACK	GOLD FLASH SEE NOTES(2-(e),2-(h))

REVISED	EC NO: SH2007-0468	2007/01/19
	DRWN:HYE01	2007/01/19
	CHKD:WANG	2007/01/19
	APPR: JNCHEN	2007/01/26
REV	DESCRIPTION	

QUALITY SYMBOLS	▽=0
	∇=0

GENERAL TOLERANCES (UNLESS SPECIFIED)	
mm	INCH
4 PLACES ± ---	± ---
3 PLACES ± ---	± ---
2 PLACES ± 0.25	± .010
1 PLACE ± 0.25	± .010
ANGULAR ± 3 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE	
MM ONLY	
DRAWN BY	DATE
DAVID HU	2004/11/05
CHECKED BY	DATE
HARVEY	2004/11/05
APPROVED BY	DATE
MATERIAL NO.	
DOCUMENT NO.	
SHEET NO.	

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
4:1	METRIC	
TITLE		
USB B TYPE CONNECTOR LEAD-FREE		
MOLEX INCORPORATED		
SD-67068-004		1 OF 1
SEE NOTES		
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